

**Notice of References Cited**

Application/Control No.

09/254,939

Applicant(s)/Patent Under  
Reexamination  
MIURA ET AL.

Examiner

Anh D. Mai

Art Unit

2814

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	V	C. P. Chang et al., A Highly Manufacturable Corner Rounding Solution for 0.18 micron Shallow Trench Isolation. 1997, IEEE, pp. 661-664
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\*A copy of this reference is not being furnished with this Office action. (See MPEP § 707.05(a).)  
Dates in MM-YYYY format are publication dates. Classifications may be US or foreign.